IN THE CLAIMS:

This listing of claims will replace all prior versions and listings of claims in the application

Listing of Claims:

- 1. (Previously Presented) A light-emitting diode comprising:
- a substrate made of group III-V nitride semiconductor;
- a first n-type semiconductor layer containing indium and formed over a main surface of the substrate;
 - a light-emitting layer formed over the first n-type semiconductor layer;
- a second n-type semiconductor layer formed between the substrate and the first n-type semiconductor layer; and
- a third n-type semiconductor layer formed between the first n-type semiconductor layer and the light-emitting layer.
 - 2. (Previously presented) The diode of claim 1, wherein the substrate is made of gallium nitride.
 - 3. (Previously presented) The diode of claim 1, wherein the main surface of the substrate is polished.
 - 4. (Previously presented) The diode of claim 3, wherein the main surface of the substrate is etched.
 - 5. (Previously presented) The diode of claim 3,

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wherein the main surface of the substrate is planarized.

- 6. (Previously presented) The diode of claim 1,
 wherein the light-emitting layer has a multiple quantum well structure formed by
 alternately stacking a quantum well layer and a barrier layer, and
 the quantum well layer has a thickness of 1 to 2.5 nm inclusive.
- 7. (Previously presented) The diode of claim 1, wherein the first n-type semiconductor layer is made of a compound whose general formula is represented by $In_aAl_bGa_{1-a-b}N$ (0<a \leq 1, 0 \leq b<1, a+b \leq 1).
 - 8. (Previously presented) The diode of claim 7, wherein the aluminum content of the first n-type semiconductor layer is 3% or lower.
 - 9. (Previously presented) The diode of claim 1, wherein the first n-type semiconductor layer has a thickness of 10 nm to 1 μ m inclusive.
 - 10. (Cancelled)
- 11. (Previously presented) The diode of claim 1, wherein the second n-type semiconductor layer is made of a compound whose general formula is represented by $In_cAl_dGa_{1-c-d}N$ ($0 \le c < 1$, $0 \le d < 1$, c+d < 1).

12. (Previously presented) The diode of claim 1,

wherein the second n-type semiconductor layer is an n-type contact layer.

- 13. (Cancelled)
- 14. (Currently amended) The diode of claim 1,

A light-emitting diode comprising:

a substrate made of group III-V nitride semiconductor;

a first n-type semiconductor layer containing indium and formed over a main surface of the substrate;

a light-emitting layer formed over the first n-type semiconductor layer;

a second n-type semiconductor layer formed between the substrate and the first n-type semiconductor layer; and

a third n-type semiconductor layer formed between the first n-type semiconductor layer and the light-emitting layer,

wherein the third n-type semiconductor layer is an n-type contact layer.

15. (Currently amended) The diode of claim 1, further comprising

A light-emitting diode comprising:

a substrate made of group III-V nitride semiconductor;

a first n-type semiconductor layer containing indium and formed over a main surface of the substrate;

a light-emitting layer formed over the first n-type semiconductor layer;

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a second n-type semiconductor layer formed between the substrate and the first n-type semiconductor layer;

a third n-type semiconductor layer formed between the first n-type semiconductor layer and the light-emitting layer; and

a fourth n-type semiconductor layer formed between the first n-type semiconductor layer and the light-emitting layer.

16. (Previously presented) The diode of claim 15,

wherein the fourth n-type semiconductor layer is made of a compound whose general formula is represented by $Al_eGa_{1-e}N$ (0 \leq e<1).

- 17. (Previously presented) The diode of claim 16, wherein the fourth n-type semiconductor layer is a cladding layer.
- 18. (Previously presented) The diode of claim 17, wherein the cladding layer has a thickness of 5 to 200 nm inclusive.
- 19. (Previously presented) The diode of claim 1, further comprising:

 an n-type contact layer which is formed between the substrate and the light-emitting layer and a portion of which is exposed;

an n-side electrode formed on the exposed portion of the n-type contact layer;
an n-type cladding layer formed between the first n-type semiconductor layer and the light-emitting layer;

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a p-type semiconductor layer formed on the light-emitting layer; and

a p-side electrode formed over the p-type semiconductor layer,

wherein the device is mounted with an element formation surface thereof facing a submount for mounting.

20. (Previously Presented) An illuminating device comprising multiple light-emitting diodes,

wherein the diodes including:

a substrate made of group III-V nitride semiconductor;

a first n-type semiconductor layer containing indium and formed over a main surface of the substrate; and

a light-emitting layer formed over the first n-type semiconductor layer.

21. (Previously presented) The diode of claim 1, wherein the light-emitting layer has a multiple quantum well structure formed by alternately stacking a quantum well layer made of group III-V nitride semiconductor not containing As, P and Sb, and a barrier layer made of group III-V nitride semiconductor.